

# MA2SD31

## Silicon epitaxial planar type

For super high speed switching

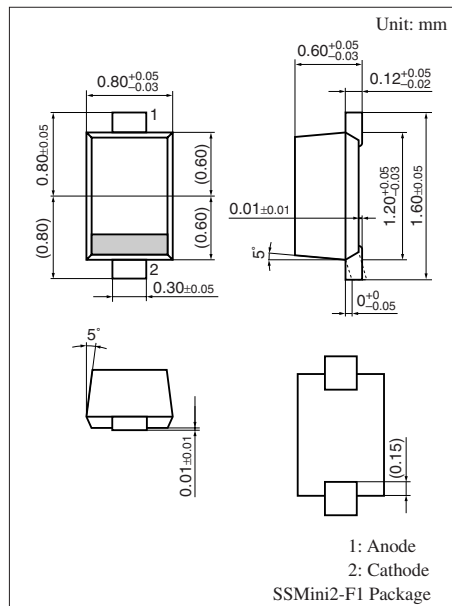
### ■ Features

- $I_{F(AV)} = 200$  mA rectification is possible.
- Low forward voltage:  $V_F < 0.47$  V (at  $I_F = 200$  mA)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	$I_{F(AV)}$	200	mA
Peak forward current	$I_{FM}$	300	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \* : The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



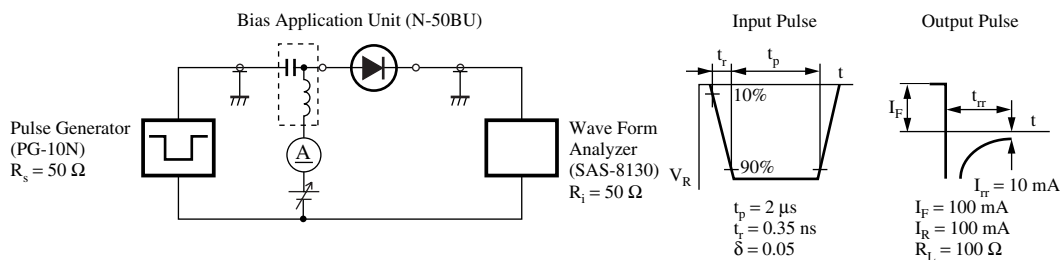
Marking Symbol: 8F

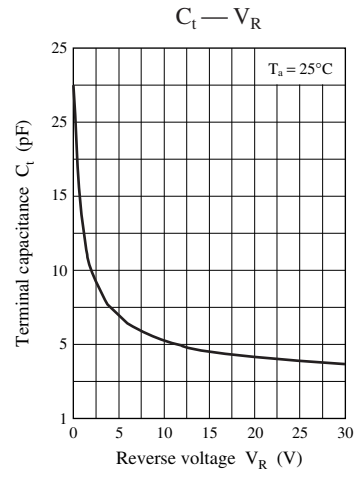
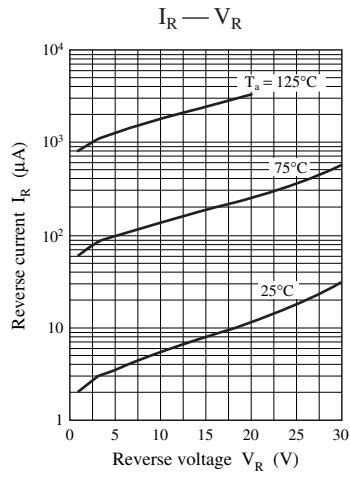
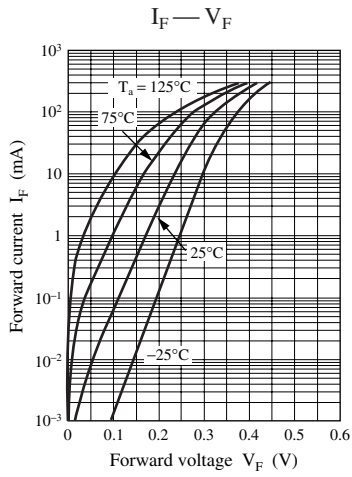
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	$I_{R1}$	$V_R = 10$ V			20	$\mu\text{A}$
	$I_{R2}$	$V_R = 30$ V			200	
Forward voltage	$V_F$	$I_F = 200$ mA		0.38	0.47	V
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		25		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA $I_{tr} = 10$ mA, $R_L = 100 \Omega$		2		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. \*:  $t_{rr}$  measurement circuit





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